

Abstracts

A compact and wideband GaAs P-HEMT distributed amplifier IC based on a micro-machined CPW

Sung-Gi Yang and Kwang-Seok Seo. "A compact and wideband GaAs P-HEMT distributed amplifier IC based on a micro-machined CPW." 2000 MTT-S International Microwave Symposium Digest 00.1 (2000 Vol. 1 [MWSYM]): 213-216.

This paper presents a new GaAs P-HEMT distributed amplifier IC that employs a micro-machined, grooved-CPW. By removing the substrate between the signal and ground metal, the grooved-CPW has small effective dielectric constant ($\epsilon_{r,eff}$) and becomes a highly inductive line. When the grooved-CPW is used in the distributed amplifier, the f_{3dB} and the chip size have been improved by about 20%. The fabricated GaAs P-HEMT distributed amplifier IC has a gain of 10 dB with $f_{3dB} > 50$ GHz.

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